

EXPRESS MAIL MAILING LABEL

Number: EX593510400US

Date of Deposit: 20 November 2001

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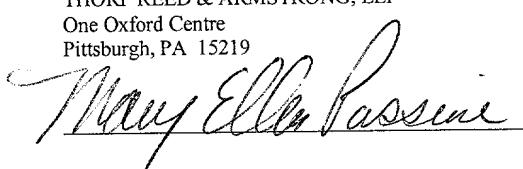
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**PATENT**

**Attorney Docket No.: DB000624-003**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicant:** Johnson et al. )

)

**Serial No.:** Not yet assigned )

)

**Filed:** 20 November 2001 )

**Entitled:** OVERMOLDING ENCAPSULATION PROCESS AND ENCAPSULATED ARTICLE MADE THEREFROM

**PRELIMINARY AMENDMENT**

Prior to the examination of the above - identified application filed herewith, please amend that application as follows.

**In the specification:**

Page 1, after the title, insert -- This application is a divisional of prior U.S. Application Serial Number 09/652,076 filed 08/31/00 which is a continuation-in-part of U.S. Application Serial Number 09/255,554 filed 02/22/1999. -- .

**In the Claims:**

Please cancel claims 1 through 25, inclusive, and add the following new claims.

-- 30. An encapsulated die not having a substrate comprising:  
a die having first and second surfaces, the first surface carrying bond pads; and  
an encapsulation material sealing the second surface of the die.

31. The encapsulated die of claim 30 wherein the encapsulation material seals the first surface of the die except for the bond pads.

32. The encapsulated die of claim 31 wherein the encapsulation material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes. --

Remarks

The instant preliminary amendment is filed to prosecute the non-elected claims from the parent application and to present new claims 30-32 drawn to an encapsulated semiconductor device for examination. No new matter has been added. A complete, clean set of the currently pending claims is attached.

Respectfully submitted,



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Dated: 20 Nov. 2001

Attorney for Applicants

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**COMPLETE, CLEAN SET OF PENDING CLAIMS**

26. An overmolded die the size of a chip scale package and not having any substrate.
27. A chip scale packaged die having no substrate.
28. An overmolded die without a substrate, comprising:  
a die having a first surface carrying electrical contacts; and  
an encapsulated material sealing the die except for the electrical contacts.
29. The overmolded die of claim 28 wherein the encapsulated material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes.
30. An encapsulated die not having a substrate comprising:  
a die having first and second surfaces, the first surface carrying bond pads; and  
an encapsulation material sealing the second surface of the die.
31. The encapsulated die of claim 30 wherein the encapsulation material seals the first surface of the die except for the bond pads.
32. The encapsulated die of claim 31 wherein the encapsulation material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes.